tesa ® XPU 58708

Product Information

200µm x-linkable polyurethane black HAF mounting tape

Product Description

tesa ® XPU 58708 is a reactive mounting tape offering high bonding strength and elasticity after curing. This black double-sided tape has no backing. It is protected by a PE-coated paper liner.

tesa ® XPU 58708 is free of halogen according to IEC 61249-2-21 and compliant with current RoHS directive.

At room temperature tesa ® XPU 58708 is not tacky. It is activated by heat and pressure applied during the assembly process.

Special features:

- Extremely high bonding performance and reliability, even on thin design gaps
- Excellent shock resistance
- Extremely low oozing ratio
- Black design

Application Fields

tesa ® XPU 58708 is especially recommended for structural bonding of various substrates inside electronic devices:

- Bonding of plastics
- Bonding of metals
- Bonding of electronic components

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

Product Construction

• Type of liner	PE-coated paper	• Total thickness	200 µm
• Backing material	none	• Color	black
• Type of adhesive	crosslinkable polyurethane		

For latest information on this product please visit http://l.tesa.com/?ip=58708

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Properties/Performance Values

- Bonding strength (push-out) 4 N/mm^2

Additional Information

Technical recommendations:

tesa® XPU 58708 is not self-adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

• Pre-lamination

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

Temperature[1] 55-65 °C

Pressure[2] 3 bar

Time 5 – 20 s

Short-time exposure to 65 °C bond line temperature during pre-lamination does not affect the final bonding potential.

2. Bonding

Remove the liner from tape after the pre-lamination step.Position the second component.

Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

2.1. PC/PC:Setting:

• Temperature[1] 80 – 140 °C

• Pressure[2] 5 bar

• Time 10 – 120 s

2.2. AL/PC:Setting:

• Temperature[1] 110 – 190 °C

• Pressure[2] 5 bar

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Additional Information

• Time 20 – 120 s

Short cycle times can be achieved at high bond line temperatures. For activation at low temperatures, increase the heat-press time. To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours. Bonding strength values were obtained under standard laboratory conditions. PC/PC: bonding conditions: temperature = 110 °C

(120 °C jig); pressure = 5 bar; time = 60 sec Storage: tesa® recommends storage in original packaging in cool and dry conditions.

• 'Pre-lamination' and 'Bonding' temperature refer to the data that is measured in the bond line.

• 'Pre-lamination' and 'Bonding' pressure refer to the force that is transferred from jig surface directly to the bonding area.

Disclaimer

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